

REMARKS

The present Amendment is in response to the Office Action mailed September 9, 2004. Enclosed herewith is a Petition requesting a three-month extension of time for resetting the deadline for responding to the Office Action from December 9, 2004, to and including March 9, 2005.

As an initial matter, Applicants acknowledge and appreciate the Examiner's indication that claims 7, 8, 13 and 18 are allowed.

In the present Amendment, Applicants have amended claim 1 to recite that the "adhesion promoter" is an --organic adhesion promoter--. Applicants have also added new claim 20, which depends from claim 1, to recite that the organic adhesion promoter can be an acrylic adhesive, a polyimide adhesive, a thermoplastic adhesive, a silane coupling agent or a fluorinated silane coupling agent. Support for the amendment to claim 1 and new claim 20 is found, inter alia, in paragraph 39 of the originally filed specification.

In the Office Action, the Examiner rejected claim 1 under 35 U.S.C. § 102(b) as being anticipated by U.S. Patent No. 5,280,139 to Suppelsa et al. Referring to FIGS. 1 and 2 thereof, Suppelsa discloses a microelectronic assembly 10 including a substrate 12 and a metal adhesive layer 14 that provides adhesion between the substrate 12 and a conductive runner 16. The portion of the conductive runner 16 that is not in contact with the adhesive layer 14 has "minimal" adhesion with the substrate 12, while the portion in contact with the metal adhesive layer 14 has greater or "maximum" adhesion with the substrate 12. As noted above, claim 1 has been amended to recite that the "adhesion promoter" is an "organic adhesion promoter." As amended, claim 1 is unanticipated by Suppelsa because the cited reference does not teach or suggest a

connection component having "an organic adhesion promoter." New claim 20 is unanticipated because the cited reference does not disclose an organic adhesion promoter made of acrylic adhesive, a polyimide adhesive, a thermoplastic adhesive, a silane coupling agent or a fluorinated silane coupling agent. Claim 20 is also unanticipated, *inter alia*, by virtue of its dependence from claim 1, which is unanticipated for the reasons set forth above.

In the Office Action, the Examiner also rejected claims 5 and 19 under 35 U.S.C. § 102(b) as being anticipated by U.S. Patent No. 5,489,749 to DiStefano et al. Referring to FIG. 2 thereof, DiStefano discloses a connection component including a supporting structure 30 having a flexible top dielectric layer 32 and a bottom compliant dielectric layer 34. The supporting structure 30 has four elongated gaps 40 extending from a top surface 36 of the supporting structure to a bottom surface 38 of the supporting structure. The elongated gaps 40 divide supporting structure 30 into an interior portion 42 and four strip-like outer securement elements 44 disposed outside of the gaps. The connection component includes a plurality of central terminals 48 disposed on central region 42 and a plurality of outside terminals 50 disposed on securement elements 44. Each central terminal 48 is associated with a central terminal lead 52, whereas each outside terminal 50 is associated with an outside terminal lead 54. Each central terminal lead includes an elongated connection section 56 extending across the associated gap 40. A first end 58 of each connection section 56 lies at the first side 60 of the gap 40 and the second end 62 of each connection section 56 lies adjacent to the second opposite side 64 of the gap 40, adjacent the securement element 44. Each lead also includes a frangible section 72. Referring to FIG. 5,

the leads 56 may be detached at the frangible section for being bonded to electrical contacts 102 on a semiconductor chip 98.

In response to the Examiner's rejection of claim 5, Applicants respectfully assert that the DiStefano '749 patent does not teach that the release interfaces are "formed by locally heating the tip end of the corresponding lead." In fact, the DiStefano '749 patent actually teaches away from the claimed invention, because it teaches using heat for permanently attaching the tip end of a lead to a contact pad, while claim 5 of the present application requires using heat to release the tip end of a lead. In addition, Applicants respectfully assert that claim 5 is unanticipated because DiStefano does not teach a connection component with "a plurality of leads disposed on the top surface of said support structure." As shown in FIG. 2 thereof, DiStefano's leads 52, 54 are disposed between top dielectric layer 32 and bottom dielectric layer 34. For all of the above reasons, Applicants respectfully assert that claim 5 is unanticipated by the DiStefano '749 patent and is otherwise allowable.

Regarding the rejection of claim 19 under the DiStefano '749 patent, Applicants respectfully assert that the cited reference does not teach the specific limitations recited in subparagraphs (b), (c) and (d) of claim 19. For example, the DiStefano '749 patent does not teach a connection component including a support structure having a "top surface" with "a plurality of first bonding pads disposed on the top surface" and "a plurality of second bonding pads disposed on the top surface." The Examiner asserts that DiStefano's chip contacts 102 (FIG. 5) are "disposed on the top surface" of the support structure. Applicants respectfully disagree with this conclusion because the contacts 102 are provided on a chip 98 and not "on the top surface" of a support structure as required

by claim 19. DiStefano also does not disclose a connection component having "a plurality of leads, wherein each lead has a terminal end permanently connected to one of the plurality of first bonding pads; and a tip end connected to the associated second bonding pad and offset from the terminal end; wherein the permanent connection between the terminal end and the first bonding pad is stronger than the connection between the tip end and the associated second bonding pad." For all of these reasons, claim 19 is unanticipated by the DiStefano '749 patent and is otherwise allowable.

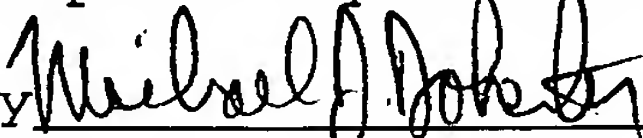
As it is believed that all of the rejections set forth in the Official Action have been fully met, favorable reconsideration and allowance are earnestly solicited.

If, however, for any reason the Examiner does not believe that such action can be taken at this time, it is respectfully requested that he telephone Applicants' attorney at (908) 654-5000 in order to overcome any additional objections which he might have.

If there are any additional charges in connection with this requested amendment, the Examiner is authorized to charge Deposit Account No. 12-1095 therefor.

Dated: March 8, 2005

Respectfully submitted,

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